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Application No. 10/722,116

Filed: November 25, 2003

TC Art Unit: 1773

Confirmation No.: 4859

AMENDMENT TO THE CLAIMS

1. (Previously Presented) A conductive resin molded product comprising:

a resin insulating skin obtained from molding a composite containing a non-conductive resin and a carbon nano material by controlling an amount of the carbon nano material to be composited with the non-conductive resin; and

a conductive core covered by said resin insulating skin, wherein a ratio of a carbon nano material to be composited with said non-conductive resin is less than about 15 weight percent based on the composite.

2. (Previously Presented) A molding method for producing a conductive resin molded product, said method comprising the steps of:

plasticizing a composite material containing a nonconductive resin and a carbon nano material; and

injection molding thus plasticized material into a mold cavity to produce the conductive resin molded product comprising a resin insulating skin and a conductive core covered with said skin, an amount of the carbon nano material to be composited with the non-conductive resin being controlled so as to form the resin insulating skin in contact with a cavity face during said injection molding, wherein a ratio of a carbon nano material to be composited with said non-conductive resin is less than about 15 weight percent based on the composite.

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3. (Canceled)